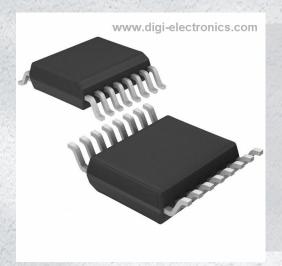


PI6C557-03BQEX Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number PI6C557-03BQEX-DG

Manufacturer Diodes Incorporated

Manufacturer Product Number PI6C557-03BQEX

Description IC CLOCK GENERATOR 16QSOP

Detailed Description Ethernet, PCI Express (PCIe) IC 200MHz 1 Output 16

-QSOP



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
PI6C557-03BQEX	Diodes Incorporated
Series:	Product Status:
-	Active
DiGi-Electronics Programmable:	PLL:
Not Verified	Yes
Main Purpose:	Input:
Ethernet, PCI Express (PCIe)	HCSL, Crystal
Output:	Number of Circuits:
HCSL, LVDS	1
Ratio - Input:Output:	Differential - Input:Output:
1:2	No/Yes
Frequency - Max:	Voltage - Supply:
200MHz	3V ~ 3.6V
Operating Temperature:	Mounting Type:
-40°C ~ 85°C	Surface Mount
Package / Case:	Supplier Device Package:
16-SSOP (0.154", 3.90mm Width)	16-QSOP
Base Product Number:	
PI6C557	

Environmental & Export classification

8542.39.0001

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	





PCle 3.0 Clock Generator with 2 HCSL Outputs

Features

- PCIe® 3.0 compliant
 - PCIe 3.0 Phase jitter 0.45ps RMS (High Freq. Typ.)
- LVDS compatible outputs
- Supply voltage of 3.3V ±10%
- 25MHz crystal or clock input frequency
- HCSL outputs, 0.8V Current mode differential pair
- Jitter 35ps cycle-to-cycle (typ)
- Spread of -0.5%, -0.75%, and no spread
- Industrial temperature range
- Spread Bypass option available
- Spread and frequency selection via external pins
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

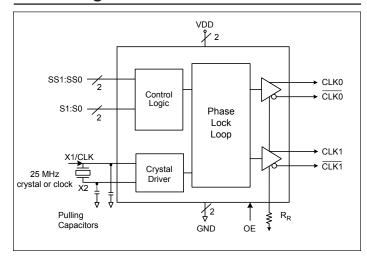
- Packaging: (Pb-free and Green)
 - 16-pin TSSOP (L16)
 - 16-pin QSOP (Q16)

Description

The DIODES™ PI6C557-03B is a spread spectrum clock generator compliant with PCI Express 3.0 and Ethernet requirements. The device can be used in PC or embedded systems to substantially reduce Electromagnetic Interference (EMI).

The PI6C557-03B provides two differential (HCSL) or LVDS spread spectrum outputs. The PI6C557-03B is configured to select spread and clock selection. Using Diodes' patented Phase-Locked Loop (PLL) techniques, the device takes a 25MHz crystal input and produces two pairs of differential outputs (HCSL) at 25MHz, 100MHz, 125MHz and 200MHz clock frequencies. It also provides spread selection of -0.5%, -0.75%, and no spread.

Block Diagram



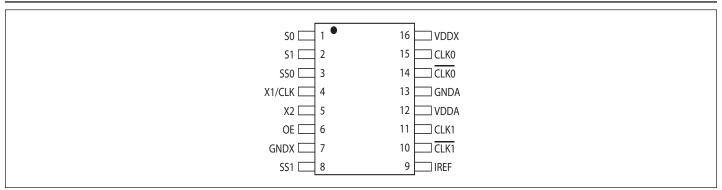
Notes

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.





Pin Configuration



Pin Description

Pin #	Pin Name	I/O Type	Description
1	S0	Input	Select pin 0 (Internal pull-up resistor). See Table 1.
2	S1	Input	Select pin 1 (Internal pull-up resistor). See Table 1.
3	SS0	Input	Spread Select pin 0 (Internal pull-up resistor). See Table 2.
4	X1/CLK	Input	Crystal or clock input. Connect to a 25MHz crystal or single ended clock.
5	X2	Output	Crystal connection. Leave unconnected for clock input.
6	OE	Input	Output enable. Internal pull-up resistor.
7	GNDX	Power	Crystal ground pin.
8	SS1	Input	Spread Select pin 1 (Internal pull-up resistor). See Table 2.
9	IREF	Output	Precision resistor attached to this pin is connected to the internal current reference.
10	CLK1	Output	HCSL compliment clock output
11	CLK1	Output	HCSL clock output
12	VDDA	Power	Connect to a +3.3V source.
13	GNDA	Power	Output and analog circuit ground.
14	CLK0	Output	HCSL compliment clock output
15	CLK0	Output	HCSL clock output
16	VDDX	Power	Connect to a +3.3V source.

Table 1: Output Select Table

S1	S0	CLK(MHz)
0	0	25
0	1	100
1	0	125
1	1	200

Table 2: Spread Selection Table

SS1	SS0	Spread
0	0	No Spread
0	1	Down -0.5
1	0	Down -0.75
1	1	No Spread





Application Information

Decoupling Capacitors

Decoupling capacitors of $0.01\mu F$ should be connected between each V_{DD} pin and the ground plane and placed as close to the V_{DD} pin as possible.

Crystal

Use a 25MHz fundamental mode parallel resonant crystal with less than 300PPM of error across temperature.

Crystal Capacitors

 C_L = Crystals's load capacitance in pF

Crystal Capacitors (pF) = $(C_L - 8) *2$

For example, for a crystal with 16pF load caps, the external effective crystal cap would be 16 pF. (16-8)*2=16.

Current Source (IREF) Reference Resistor - R_R

If board target trace impedance is 50Ω ,

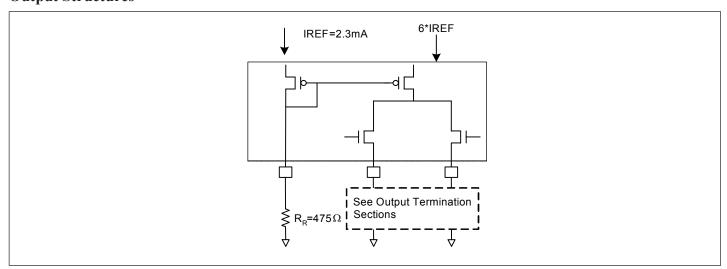
then $R_R = 475\Omega$ providing an IREF of 2.32 mA. The output current (I_{OH}) is 6*IREF.

Output Termination

The PCI Express differential clock outputs of the PI6C557-03B are open source drivers and require an external series resistor and a resistor to ground. These resistor values and their allowable locations are shown in detail in the PCI Express Layout Guidelines section.

The PI6C557-03B can be configured for LVDS compatible voltage levels. See the LVDS Compatible Layout Guidelines section.

Output Structures







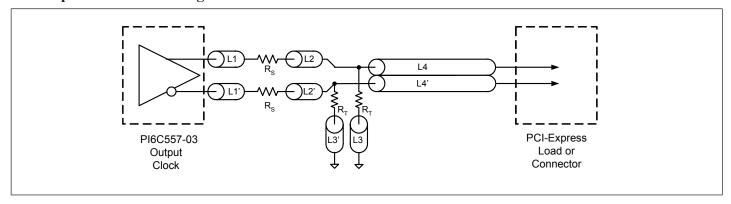
PCI Express Layout Guidelines

Common Recommendations for Differential Routing	Dimension or Value	Unit
L1 length, route as non-coupled 50Ω trace.	0.5 max	inch
L2 length, route as non-coupled 50Ω trace.	0.2 max	inch
L3 length, route as non-coupled 50Ω trace.	0.2 max	inch
R_{S}	33	Ω
R_{T}	49.9	Ω

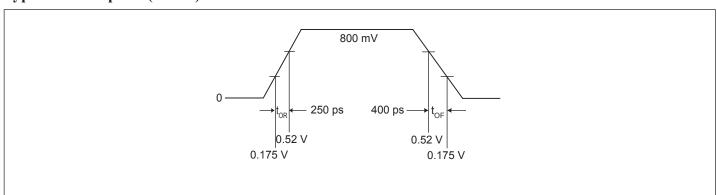
Differential Routing on a Single PCB	Dimension or Value	Unit
L4 length, route as coupled microstrip 100Ω differential trace.	2 min to 16 max	inch
L4 length, route as coupled stripline 100Ω differential trace.	1.8 min to 14.4 max	inch

Differential Routing to a PCI Express connector	Dimension or Value	Unit
L4 length, route as coupled microstrip 100Ω differential trace.	0.25 min to 14 max	inch
L4 length, route as coupled stripline 100Ω differential trace.	0.225 min to 12.6 max	inch

PCI Express Device Routing



Typical PCI Express (HCSL) Waveform



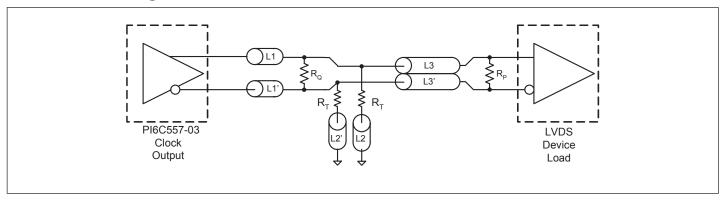




Application Information

LVDS Recommendations for Differential Routing	Dimension or Value	Unit
L1 length, route as non-coupled 50Ω trace.	0.5 max	inch
L2 length, route as non-coupled 50Ω trace.	0.2 max	inch
RP	100	Ω
RQ	100	Ω
RT	150	Ω
L3 length, route as 100Ω differential trace.		
L3 length, route as 100Ω differential trace.		

LVDS Device Routing







Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Supply Voltage to Ground Potential
All Inputs and Outputs
Ambient Operating Temperature40 to +85°C
Storage Temperature65 to +150°C
Junction Temperature
Soldering Temperature
EDS Protection (Input) 2000 V min (HBM)

Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Electrical Specifications

Recommended Operation Conditions

Parameter	Min.	Тур.	Max.	Unit
Ambient Operating Temperature	-40		+85	°C
Power Supply Voltage (measured in respect to GND)	+3.0		+3.6	V

DC Characteristics ($V_{DD} = 3.3V \pm 10\%$, $T_A = -40$ °C to +85°C)

Symbol	Parameter	Conditions		Min.	Тур.	Max.	Unit
V_{DD}	Supply Voltage			3.0	3.3	3.6	V
V _{IH}	Input High Voltage ⁽¹⁾	OE, S0, S1, SS0	, SS1	2.0		V _{DD} +0.3	V
V _{IL}	Input Low Voltage ⁽¹⁾	OE, S0, S1, SS0	, SS1	GND -0.3		0.8	V
	I _{IL} Input Leakage Current	$0 < Vin < V_{DD}$	With input pull-up and pull-downs	-20		20	μА
$\mid ext{I}_{ ext{IL}} \mid$			Without input pull- up and pull-downs	-5		5	
I_{DD}	O	$R_L = 50\Omega$, $C_L =$	2pF			95	mA
I_{DDOE}	Operating Supply Current	OE = LOW				50	mA
C _{IN}	Input Capacitance	@ 55MHz				7	pF
Cout	Output Capacitance	@ 55MHz				6	pF
L _{PIN}	Pin Inductance					5	nН
R _{OUT}	Output Resistance	CLK Outputs		3.0			kΩ

Notes:

1. Single edge is monotonic when transition through region.





HCSL Output AC Characteristics ($V_{DD} = 3.3V \pm 10\%$, $T_A = -40$ °C to +85°C)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
F _{IN}	Input Frequency			25		MHz
V _{OUT}	Output Frequency		25		200	MHz
V _{OH}	Output High Voltage (1,2)	100 MHz HCSL output @ V _{DD} = 3.3V	660	800	900	mV
V _{OL}	Output Low Voltage ^(1,2)		-150	0		mV
V _{CPA}	Crossing Point Voltage ^(1,2)	Absolute	250	350	550	mV
$V_{\rm CN}$	Crossing Point Voltage(1,2,4)	Variation over all edges			140	mV
Jcc	Jitter, Cycle-to-Cycle ^(1,3)			35	60	ps
J _{RMS2.0}	PCIe 2.0 RMS Jitter	PCIe 2.0 Test Method @ 100MHz Output			3.1	ps
Jrms3.0	PCIe 3.0 RMS Jitter	PLL L-BW @ 2M & 5M 1st H3		1.75	3	ps
		PLL L-BW @ 2M & 4M 1st H3		2.18	3	ps
		PLL H-BW @ 2M & 5M 1st H3		0.45	1	ps
		PLL H-BW @ 2M & 4M 1st H3		0.45	1	ps
MF	Modulation Frequency	Spread Spectrum	30	31.5	33	kHz
tor	Rise Time ^(1,2)	From 0.175V to 0.525V	175		700	ps
tof	Fall Time ^(1,2)	From 0.525V to 0.175V	175		700	ps
T _{SKEW}	Skew between outputs	At Crossing Point Voltage			50	ps
T _{DUTY-CYCLE}	Duty Cycle ^(1,3)		45		55	%
T _{OE}	Output Enable Time ⁽⁵⁾	All outputs			10	μs
T _{OT}	Output Disable Time ⁽⁵⁾	All outputs			10	μs
t _{STABLE}	From power-up to V _{DD} =3.3V	From Power-up V _{DD} =3.3V		3.0		ms
t_{SPREAD}	Setting period after spread change	Setting period after spread change		3.0		ms

Notes:

- 1. $R_L = 50$ -Ohm with $C_L = 2 pF$
- 2. Single-ended waveform
- 3. Differential waveform
- 4. Measured at the crossing point
- 5. CLK pins are tri-stated when OE is LOW





Thermal Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
θ_{JA}	Thermal Resistance Junction to Ambient	Still air			90	°C/W
θ_{JC}	Thermal Resistance Junction to Case				24	°C/W

Recommended Crystal Specification

Diodes Recommends:

- a) GC2500003 XTAL 49S/SMD(4.0 mm), 25M, CL=18pF, +/-30ppm http://www.pericom.com/pdf/datasheets/se/GC_GF.pdf
- b) FY2500081, SMD 5x3.2(4P), 25M, CL=18pF, +/-30ppm http://www.pericom.com/pdf/datasheets/se/FY_F9.pdf
- c) FL2500047, SMD 3.2x2.5(4P), 25M, CL=18pF, +/-20ppm http://www.pericom.com/pdf/datasheets/se/FL.pdf

Part Marking

L Package

PI6C557 -03BLE **ZYYWWXX**

Z: Die Rev YY: Year

 \bigcirc

WW: Workweek

1st X: Assembly Code 2nd X: Fab Code

Bar above fab code means Cu wire

Q Package

PI6C557 -03BQE **ZYYWWXX** \bigcirc

Z: Die Rev YY: Year

WW: Workweek

1st X: Assembly Code

2nd X: Fab Code

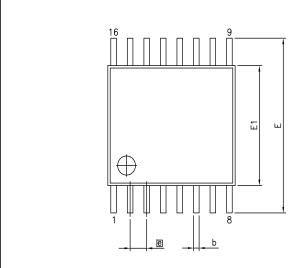
Bar above fab code means Cu wire

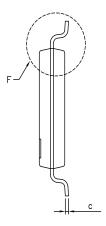




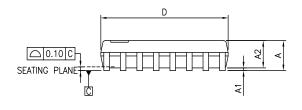
Packaging Mechanical

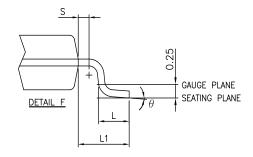
16-TSSOP (L)





SYMBOLS	MIN.	NOM.	MAX.
Α	ı	_	1.20
A1	0.05	-	0.15
A2	0.80	1.00	1.05
b	0.19	_	0.30
С	0.09	-	0.20
D	4.90	5.00	5.10
E1	4.30	4.40	4.50
E	6.20	6.40	6.60
е	0.65 BSC		
L1	1.00 REF		
L	0.45	0.60	0.75
S	0.20	_	-
θ	0°	-	8°





PERICOM Enabling Serial Connectivity

DATE: 03/24/16

1. ALL DIMENSIONS IN MILLIMETERS. ANGLES IN DEGREES.

2. JEDEC MO-153F

3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

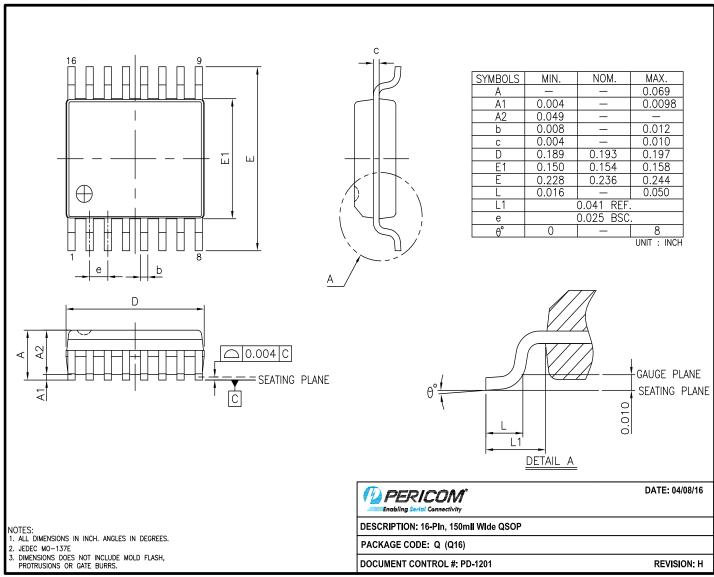
DESCRIPTION: 16-Pin, 173mil Wide TSSOP PACKAGE CODE: L (L16) DOCUMENT CONTROL #: PD-1310

REVISION: G





16-QSOP (Q)



16-0056

For latest package info.

 $please\ check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanicals-and-thermal-characteristics/packaging-mechanical-and-thermal-characteristics/packaging-mechanical-and-thermal-characteristics/packaging-mechanical-and-thermal-characteristics/packaging-mechanical-and-thermal-characteristics/packaging-mechanical-and-thermal-characteristics/packaging-mechanical-and-thermal-characteristics/packaging-mechanical-and-thermal-characteristics/packaging-mechanical-and-thermal-characteristics/packaging-mechanical-and-thermal-characteristics/packaging-mechanical-and-thermal-characteristics/packaging-mechanical-and$

Ordering Information

Ordering Code	Package Code	Package Type
PI6C557-03BLEX	L	16-pin, 173mil Wide (TSSOP)
PI6C557-03BQEX	Q	16-pin, 150mil Wide (QSOP)

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- $2. \ \ See \ https://www.diodes.com/quality/lead-free/\ for\ more\ information\ about\ Diodes\ Incorporated's\ definitions\ of\ Halogen-\ and\ Antimony-free,\ "Green"\ and\ Lead-free.$
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. E = Pb-free and Green
- 5. X suffix = Tape/Reel





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